

< C band internally matched power GaAs FET >

MGFC40V5258

5.2 - 5.8 GHz BAND / 10W

DESCRIPTION

The MGFC40V5258 is an internally impedance-matched GaAs power FET especially designed for use in 5.2-5.8 GHz band amplifiers. The hermetically sealed metal-ceramic package guarantees high reliability.

FEATURES

Class A operation Internally matched to 50(ohm) system

 High output power P1dB=10W (TYP.) @f=5.2 – 5.8GHz

 High power gain GLP=10dB (TYP.) @f=5.2 – 5.8GHz

 High power added efficiency P.A.E.=32% (TYP.) @f=5.2 – 5.8GHz

APPLICATION

• item 01: 5.2 - 5.8 GHz band power amplifier

• item 51: 5.2 - 5.8 GHz band digital radio communication

QUALITY

• IG

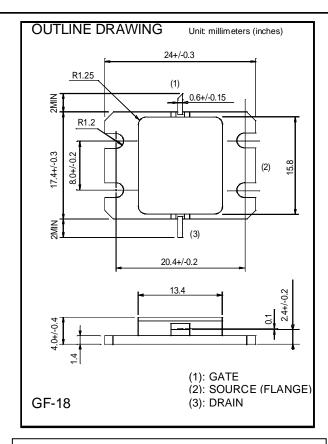
RECOMMENDED BIAS CONDITIONS

• VDS=10V • ID=2.4A • RG=50ohm

Absolute maximum ratings (Ta=25°C)

Symbol	Parameter	Ratings	Unit				
VGDO	Gate to drain breakdown voltage	-15	V				
VGSO	Gate to source breakdown voltage	-15	V				
ID	Drain current	7.5	Α				
IGR	Reverse gate current	-20	mA				
IGF	Forward gate current	42	mA				
PT *1	Total power dissipation	42.8	W				
Tch	Cannel temperature	175	°C				
Tstg	Storage temperature	-65 to +175	°C				
*1 : Tc=25°C							

1 . 10=25°C



Keep Safety first in your circuit designs! Mitsubishi Electric Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measure such as (I) placement of substitutive, auxiliary circuits, (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

Electrical characteristics (Ta=25°C)

Symbol	Parameter	Test conditions	Limits		Unit	
			Min.	Тур.	Max.	
IDSS	Saturated drain current	VDS=3V,VGS=0V	-	4.5	6	Α
gm	Transconductance	VDS=3V,ID=2.2A	-	2	-	S
VGS(off)	Gate to source cut-off voltage	VDS=3V,ID=40mA	-2	-3	-4	V
P1dB	Output power at 1dB gain compression	VDS=10V,ID(RF off)=2.4A	39.5	40.5	-	dBm
GLP	Linear Power Gain	f=5.2 – 5.8GHz	8	10	-	dB
ID	Drain current		-	2.4	-	Α
P.A.E.	Power added efficiency]	-	32	-	%
Rth(ch-c) *3	Thermal resistance	7	-	-	3.5	°C/W

^{*2 :}item -51 ,2 tone test,Po=29dBm Single Carrier Level ,f=5.0GHz,delta f=10MHz

^{*3:} Channel-case

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